

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3677	packag\$3 and chip and pads and (bump or solder) and substrate near5 (cavity or trench or hole or via or recess)	USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/05 17:19
L2	1383	1 and trace\$1	USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/05 16:27
L3	700	2 and dielectric	USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/05 17:20
L4	524	3 and "257"/\$.ccls.	USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/05 17:19
L5	2659	packag\$3 and chip and pads and (bump or solder) and substrate near5 (cavity or trench or hole or via or recess)	US-PGPUB	OR	OFF	2006/03/05 17:19
L6	0	3 and "257"/\$.ccls.	US-PGPUB	OR	OFF	2006/03/05 17:19
L7	0	2 and dielectric	US-PGPUB	OR	OFF	2006/03/05 17:20

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L2	1383	1 and trace\$1	USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/05 16:27
L3	700	2 and dielectric	USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/05 16:30
L4	524	3 and "257"/\$.ccls.	USPAT; EPO; JPO; DERWENT	OR	OFF	2006/03/05 16:31